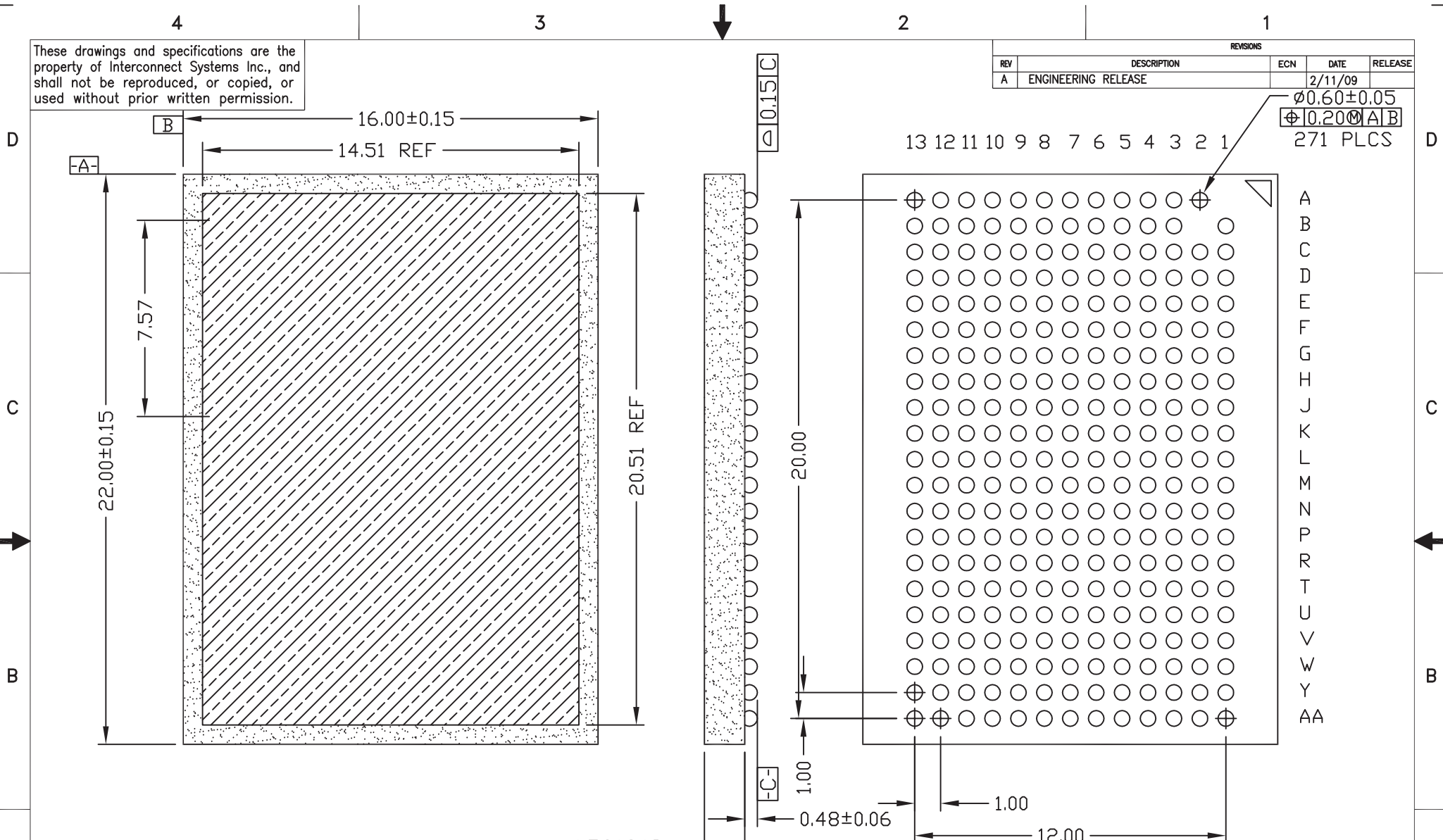


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REVISIONS				
REV	DESCRIPTION	ECN	DATE	RELEASE
A	ENGINEERING RELEASE		2/11/09	



$\phi 0.60 \pm 0.05$
 $\phi 0.20 \pm 0.05$
 271 PLCS

NOTES

- SUBSTRATE: BT LAMINATE
- SOLDER BALL ALLOY: 63/37 Sn/Pb, LEAD FREE OPTION: SAC305
- EXCLUDING BALLS, PACKAGE MEETS RoHS DIRECTIVE.

UNLESS OTHERWISE SPECIFIED:
 DIMENSIONS ARE IN INCHES
 TOLERANCES:
 ANGLES: \pm
 FRACTIONS: $\pm 1/64$
 DECIMALS:
 .XX ± 0.10
 .XXX ± 0.005
 .XXXX ± 0.0005

CONTRACT NO.		LOGIC DEVICES 1375 Geneva Drive Sunnyvale, CA 94089	
DRAWN BY	DATE	TITLE	
DESIGNER	DATE	271 PBGA, 1mm pitch	
CHECKER	DATE		
QA	DATE	SIZE	SCALE
PROCESS ENG.	DATE	A	NONE
		DRAWING NO.	REV
		MD-BG2	B
		FINISHED ASSY: VARIOUS	SHEET 1 OF 2